

*Attorney docket OHG 143***IN THE SPECIFICATION***Paragraph at page 12, line 18:*

Fig. 1(A) is a plan view seen from above showing in outline the constitution of a semiconductor device according to a first embodiment of this invention, and Fig. 1(B) is a plan view showing an expanded outline of the main parts of a region of Fig. 1(A) in order to illustrate the connection relationship between a wiring pattern and electrode pads, while Fig. 1(C) is a more detailed plan view according to Fig. 1(B), and Fig. 1(D) is a more detailed plan view according to Fig. 1(A), but is a cross-sectional view taken along line II-II of Fig. 1(C);

Paragraph at page 12, line 24:

Fig. 2(A) is a schematic sectional view showing a cross section of the semiconductor device according to the first embodiment severed along a broken line I-I in Fig. 1(A), and Fig. 2(B) is a more detailed schematic view according to Fig. 2(B);

Paragraph at page 15, line 14:

A semiconductor device according to a first embodiment of this invention will now be described with reference to Figs. 1 and 2. Fig. 1(A) is a plan view seen from above showing in outline the constitution of the semiconductor device of the first embodiment, and Fig. 1(B) is a plan view showing an expanded outline of the main parts of a partial region of Fig. 1(A) in order to illustrate the connection relationship between a wiring pattern and electrode pads. Fig. 2(A) is a schematic sectional view showing a cross section severed along a broken line I-I in Fig. 1(A).

Page 18, between lines 8 and 9, add new paragraph:

In Fig. 2(B), reference numerals 46a and 46b respectively indicate the top surface and side surface of the electrode posts 46, while reference numerals 49a and 49b respectively indicate a nickel film as a barrier metal layer and thin oxidation layer as a barrier metal layer.

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Paragraph at page 18, line 9:

Here, using Fig. 1(B), the connection relationships between the electrode pads 34 and wiring patterns 42 will be described. A partial region (the region surrounded by the solid line) 11 of Fig. 1(A) has been expanded and illustrated in order to facilitate understanding of these connection relationships. The wiring patterns 42 are constituted such that each of the electrode posts (shown as 46 in Fig. 2(A)) connected to the lower portion of the external terminals 47 is regularly and electrically connected to a corresponding electrode pad 34. A long wire 42a, a medium wire 42b, and a short wire 42c, for example, are provided as the wires which constitute each wiring pattern 42. These wires 42a, 42b, and 42c are respectively connected to the corresponding electrode pads 34 in a one-on-one connection relationship of one wire to one electrode pad. Figs. 1(A) and 1(B) show that the electrode pads 34 are arranged in a line along a first direction (vertical in Fig. 1(B)), and the external terminals 47 are arranged in another line along a second direction (horizontal in Fig. 1(B)) that is perpendicular to the first direction, and the external terminals 47 are electrically connected to the electrode pads in a one-on-one connection relationship by the wiring patterns 42.

Paragraph at page 19, line 1:

Accordingly, the portion 42X of the wiring patterns 42 in the vicinity of this boundary is preferably comprised of thicker and / or wider wire over a certain length. This is illustrated in plan-view Fig. 1(C) and cross-sectional view 1(D), where the thicker or wider portion is shown in greater detail inside the dashed-line oval indicated by reference numeral 42X.